The SolderStar PRO - VP system allows users of batch and in-line vapour phase soldering machines to fully profile their products in the same way as a conventional reflow oven.

The system includes the SolderStar PRO data-logger combined with a sealed light-weight heat shield capable of operating in the pre-heat, vapour reflow and vacuum stages of the machine.

Data can be passed to a nearby PC via wireless telemetry allowing the profile to be viewed in real-time by the user.

Once data capture is complete the heat shield can be opened and the datalogger removed, allowing rapid cool down cycles and minimising the risk of overheating the profiling unit.

### System Advantages

- Standard data logger and heat shield solution maximised datalogger protection
- Extendable for control of wave / selective or reflow soldering
- Unique SmartLink connection system provides quick datalogger connection to a range of products and accessories
- Low mass thermal shield provides minimal impact to process
- Error free Wireless Telemetry with automatic offload and catchup ensure no gaps in data transmission
- Extendable Wireless range > 100 Metres from machine
### Datalogger

**Size/Weight**
125mm x 52mm x 9mm, 110g

**Channels**
upto 16 Channel Versions Available

**Memory**
120,000 Memory Points

**Sampling**
0.1s - 10 Minutes

**Measurement Range**
-150 - 600 °C

**Accuracy**
±0.5 °C

**Resolution**
±0.02 °C

**Max. Internal Temperature**
+85 °C (Auto Shutdown on over temp.)

**Power**
Rechargeable High Temperature Nimh

**Communications**
USB (Type A - Mini B) or 2.4Ghz Wireless

**Thermocouples**
Type K, EN 05842:1993
Class 1 / ANSI MC 96.1

### Technical Data

- **Size/Weight**: 125mm x 52mm x 9mm, 110g
- **Channels**: upto 16 Channel Versions Available
- **Memory**: 120,000 Memory Points
- **Sampling**: 0.1s - 10 Minutes
- **Measurement Range**: -150 - 600 °C
- **Accuracy**: ±0.5 °C
- **Resolution**: ±0.02 °C
- **Max. Internal Temperature**: +85 °C (Auto Shutdown on over temp.)
- **Power**: Rechargeable High Temperature Nimh
- **Communications**: USB (Type A - Mini B) or 2.4Ghz Wireless
- **Thermocouples**: Type K, EN 05842:1993
- **Class 1 / ANSI MC 96.1**

### Heatshield

**Supplied Model**
HS-VP006-01

**Material**
Aluminium - PTFE Coated

**Weight**
6 Channel Version: 620g

**Thermal Protection Duration**

<table>
<thead>
<tr>
<th>Temperature (°C)</th>
<th>Survival Time (Minutes)</th>
</tr>
</thead>
<tbody>
<tr>
<td>100</td>
<td>10</td>
</tr>
<tr>
<td>150</td>
<td>20</td>
</tr>
<tr>
<td>200</td>
<td>30</td>
</tr>
<tr>
<td>250</td>
<td>40</td>
</tr>
</tbody>
</table>

Other heatshield sizes are available for special process requirements.

### Wireless Telemetry Option

**Frequency**
2.4GHZ Transceiver

**Channels**
128 Individual Channels

**Protocol**
Zigbee PRO - Duplex Transmission

### Software

**Compatibility**
Windows™ XP Vista/Windows 7/8/10
32 & 64 Bit

**Language Support**
English, French, German, Italian, Portuguese, Spanish & Chinese

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**For more information contact your regional Solderstar office**

**Solderstar Ltd**
Unit C2 - Castle Park Industrial Estate
Bower Street, Oldham, UK OL1 3LN
Tel: +44 (0)1706 354846
Fax: +44 (0)1706 675296
Email: info@solderstar.co.uk

**Solderstar LLC**
4500 140th Avenue North, Suite 101
Clearwater, FL 33762, USA
Tel: +1 (727) 461 2270
Fax: +1 (727) 538 4237
Email: info@solderstar.com

**Solderstar (Germany)**
Dehmer Str. 48
32549 Bad Oeynhausen, Germany
Tel: +49 5731 3002811
Fax: +49 5731 3002814
Email: info@solderstar.de

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**Standard Equipment**
- 6 Channel Vapour Phase Barrier
- 6 Type K thermocouples
- Equipment case

*This product can be supplied as a stand-alone system complete with datalogger, or as an accessory to an existing SolderStar system. Please contact SolderStar or your local supplier for the optimum configuration for your soldering processes.*

**Optional Equipment**
- 8 Channel Barrier
- 2.4Ghz Wireless Telemetry
- USB powered Wireless range extender

**Additional Process Support**

3 in One

**REFLOW • WAVE • VAPOUR**

A range of process specific accessories are available to extend the system for use with Reflow Wave/Selective Soldering and Vapour Phase processes.

**Specification subject to change without notification**